



# Product data sheet

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SOD-123FL

Applications General rectification

#### Features

- Small power mold type.(PMDU)
- Low I<sub>R</sub>.
- High reliability.

**Construction** Silicon epitaxial planar



## Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Reverse voltage (repetitive peak)	V <sub>RM</sub>	60	V
Reverse voltage (DC)	VR	60	V
Average rectified forward current	lo	1	A
Forward current surge peak (60Hz · 1cyc)	I <sub>FSM</sub>	30	A
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-40 to +150	°C

(\*1)Mounted on epoxy board. 180°Half sine wave

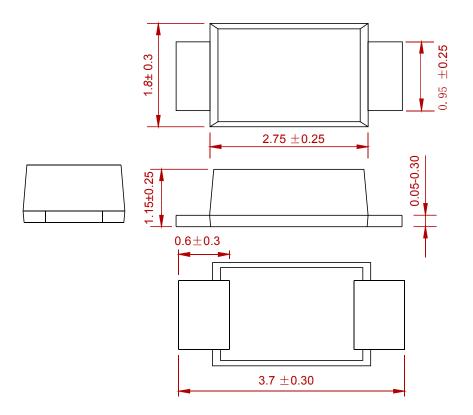
#### Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	VF	-	0.49	0.55	V	I <sub>F</sub> =1.0A
Reverse current	I <sub>R</sub>	-	7.0	50	μA	V <sub>R</sub> =60V
Capacitance terminals	Ct	-	40	-	pF	V <sub>R</sub> =10V , f=1MHz



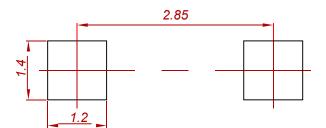


## PACKAGE MECHANICAL DATA



Dimensions in millimeters

## Suggested Pad Layout



## Note:

1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
RB160M-60	SOD-123FL	3000



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